

1 36. The microelectronic package of claim 35, wherein said encapsulation
2 material is adjacent at least a portion of said at least one heat dissipation device.

1 37. The microelectronic package of claim 31, wherein said microelectronic die
2 further includes a back surface; and wherein at least one surface of said encapsulation
3 material is substantially planar to said microelectronic die.

✓
Please cancel claims 5-23, without prejudice.

REMARKS

Claims 1-4 and 24-37 remain in the application. Claims 24-37 have been added to more clearly define the present invention. These amendments are supported throughout the specifications and the figures.

The application was originally filed with twenty-three claims with four independent claims. Nineteen claims have been cancelled without prejudice including three independent claims. Fourteen claims including two independent have been added. Therefore, no fee for the additional claims is believed due.

Please forward further communications to the address of record. If the Examiner needs to contact the below-signed attorney to further the prosecution of the application, the contact number is (503) 712-1682.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Robert G. Winkle', written over a horizontal line.

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